AMENDMENTS TO THE CLAIMS

Please cancel claims 1-7 without prejudice or disclaimer of their underlying subject matter.

1-7. (canceled)

Please add the following new claims.

8. (new) A marking method comprising the steps of:

emitting a laser beam;

deflecting said emitted laser beam in accordance with a frequency of an X applied electrical signal and a frequency of a Y applied electrical signal;

separating said deflected laser beam into a plurality of laser beams;

scanning a first of said plurality of laser beams onto a substrate; and

scanning a second of said plurality of laser beams onto said substrate.

9. (new) The laser marking method according to claim 8, wherein, prior to the step of deflecting said laser beam, the method further comprises the step of:

adjusting said emitted laser beam in a predetermined beam diameter and collimation.

10. (new) The laser marking method according to claim 8, wherein, in the step of deflecting said emitted laser beam, said X applied electrical signal and said Y applied electrical signal control a deflection angle of said emitted laser beam.

11. (new) The laser marking method according to claim 8, wherein the step of scanning said first of said plurality of laser beams performs a two-dimensionally scan.

12. (new) The laser marking method according to claim 8, wherein, in the step of scanning said first of said plurality of laser beams, the method further comprises the step of:

correcting a shift of a focal distance.

13. (new) The laser marking method according to claim 8, wherein the step of scanning said second of said plurality of laser beams performs a two-dimensionally scan.

14. (new) The laser marking method according to claim 8, wherein, in the step of scanning said second of said plurality of laser beams, the method further comprises the step of:

correcting a shift of a focal distance.

15. (new) The laser marking method according to claim 8, wherein a first mark is positioned on said substrate spaced away from a second mark,

the step of scanning said first of said plurality of laser beams onto a substrate forms said first mark, and the step of scanning said second of said plurality of laser beams onto a substrate forms said second mark.

16. (new) The laser marking method according to claim 8, wherein said substrate is a liquid crystal glass substrate.

17. (new) The laser marking method according to claim 8, wherein said substrate is coated with a photoresist.

18. (new) A marking apparatus comprising:

a laser oscillator mechanism adapted to emit a laser beam;

an acoustic deflector mechanism adapted to deflect said emitted laser beam in accordance with a frequency of an X applied electrical signal and a frequency of a Y applied electrical signal;

a separator mechanism adapted to separate said deflected laser beam into a plurality of laser beams;

a first galvanometer scanner mechanism adapted to scan a first of said plurality of laser beams onto a substrate; and

a second galvanometer scanner mechanism adapted to scan a second of said plurality of laser beams onto said substrate.

19. (new) The laser marking apparatus according to claim 18, wherein said acoustic deflector mechanism includes:

an X acoustooptic deflector adapted to output an X acoustooptic deflected laser beam by deflecting said emitted laser beam in accordance with said frequency of said X applied electrical signal, and

a Y acoustooptic deflector adapted to output said deflected laser beam by deflecting said X acoustooptic deflected laser beam in accordance with said frequency of said Y applied electrical signal.

20. (new) The laser marking apparatus according to claim 19, wherein the X applied electrical signal and the Y applied electrical signal control a deflection angle of the emitted laser beam.

21. (new) The laser marking apparatus according to claim 18, further comprising:

a first f θ lens between said first galvanometer scanner mechanism and said substrate, said first f θ lens being adapted to adjust a first focal distance.

22. (new) The laser marking apparatus according to claim 18, wherein said first galvanometer scanner mechanism includes a first X galvanometer scanner and a first Y galvanometer scanner,

said first X galvanometer scanner being adapted to scan said first of said plurality of laser beams onto said first Y galvanometer scanner, and

said first Y galvanometer scanner being adapted to scan said first of said plurality of laser beams onto said substrate.

23. (new) The laser marking apparatus according to claim 18, further comprising:

a second f θ lens between said second galvanometer scanner mechanism and said substrate, said second f θ lens being adapted to adjust a second focal distance.

24. (new) The laser marking apparatus according to claim 18, wherein said second galvanometer scanner mechanism includes a second X galvanometer scanner and a second Y galvanometer scanner,

said second X galvanometer scanner being adapted to scan said second of said plurality of laser beams onto said second Y galvanometer scanner, and

said second Y galvanometer scanner being adapted to scan said second of said plurality of laser beams onto said substrate.

25. (new) The laser marking apparatus according to claim 18, wherein, on said substrate, said first of said plurality of laser beams forms a first mark and said second of said plurality of laser beams forms a second mark,

said first mark being positioned spaced away from said second mark.

26. (new) The laser marking apparatus according to claim 18, wherein said first of said plurality of laser beams is scanned onto said substrate at a first location, and said second of said plurality of laser beams is scanned onto said substrate at a location other than said first location.

27. (new) The laser marking apparatus according to claim 18, wherein said substrate is a liquid crystal glass substrate.

28. (new) The laser marking apparatus according to claim 18, wherein said substrate is coated with a photoresist.